

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 843.37558VX1	SERIAL NO. 09/903 U.S. PTO 09/9036613
	APPLICANT M. FUNABASHI	
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U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AM	AA 4,239,661	12/16/80	Muraoka et al. 438	252	541	471
	AB 4,958,061	09/18/90	Wakabayashi et al.	219	411	
	AC 5,286,678	02/15/94	Rastogi 438	437	200	301
	AD 5,288,651	02/22/94	Nakazawa 438	437	31	145
	AE 5,290,361	03/01/94	Hayashida et al.	134	2	
	AF 5,447,568	09/05/95	Hayakawa et al. 118	437	187	715
	AG 5,466,389	11/14/95	Ilardi et al. 510	252	156	175
	AH 5,783,495	07/21/98	Li et al.	438	738	
	AI 5,972,862	10/26/99	Torii et al.	510	175	
	AJ 5,855,811	01/05/99	Grieger et al.	252	79.3	
	AK 5,679,171	10/1997	Saga et al.	134	3	
↓	AL 6,096,650	08/2000	Robinson et al.	438	689	

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
AM	AM 03-109732-A	05/1991	Japan	H01L	21/304		
	04-101418-A	04/1992	Japan	H01L	21/304		
	07-153728-A	06/1995	Japan	H01L	21/304		
	08-250461-A	09/1996	Japan	H01L	21/304		
	08-306650-A	11/1996	Japan	H01L	21/304		
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↓	09-286999-A	11/1997	Japan	H01L	21/304		

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AM	AN	Oimet et al., "Defect Reduction and Cost Savings through Re-Inventing RCA Cleans", <i>IEEE/SEMI Advanced Semiconductor Manufacturing Conference</i> (1996), p. 308-313
	AO	Watanabe et al., "Influence of particles/impurity metals in RCA cleaning solutions on surface contamination", <i>International Symposium on Semiconductor Manufacturing</i> (1994), pp. 99-102
	AP	Osaka and Hattori, "Influence of Initial Wafer Cleanliness on Metal Removal Efficiency in Immersion SC-1 Cleaning: Limitation of Immersion-Type Wet Cleaning", <i>IEEE Trans. on Semiconductor Manufacturing</i> , Vol. 11, No. 1 (02/1998), pp. 20-24
	AQ	Ridley, Sr. et al., "Advanced Aqueous Wafer Cleaning in Power Semiconductor Device Manufacturing", <i>IEEE/SEMI Adv. Semiconductor Man. Conf.</i> (1998), pp. 235-242
↓	AR	"Improved Organic Clean for Removing Contaminants on Semiconductor Wafer Surfaces", <i>IBM Tech. Dis. Bulletin</i> , March 1985
↓	AS	"Improvements to MOS Retention Time Based Tests", <i>IBM Tech. Dis. Bulletin</i> , May 1984
Examiner		Date Considered
J. H. Malsam		11-13-2001